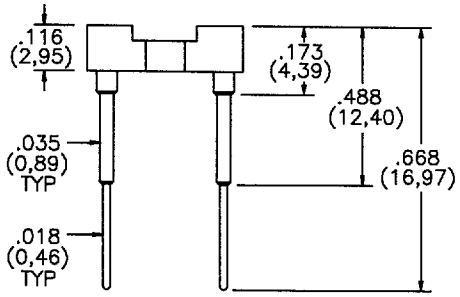
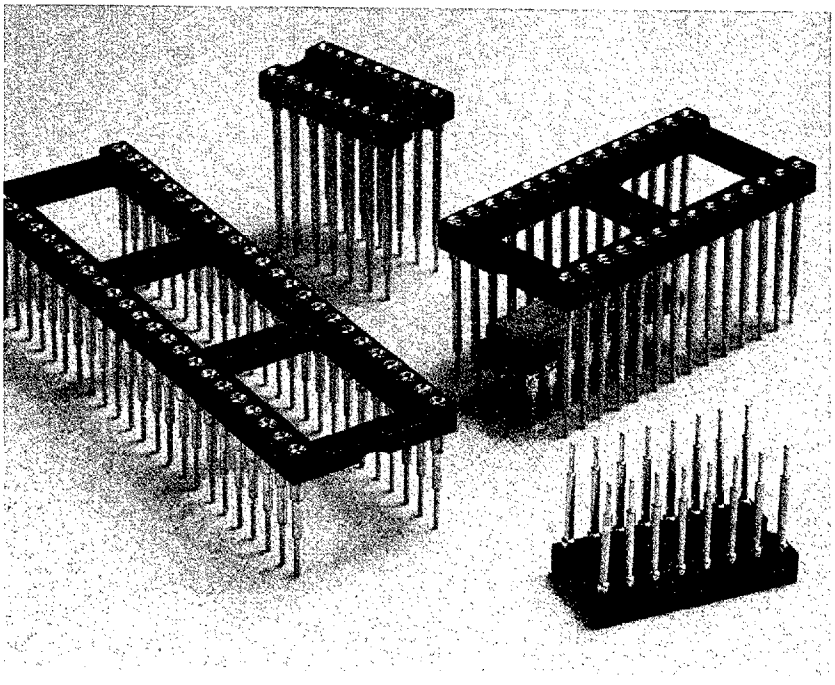


Specify	Contact/Shell
314B	30µ" Gold/10µ" Gold
PTH =	.024 ± .003



Elevated DIP Sockets

How to Order

DIP - 320 - 300B - CF - R

- DIP: Product Code
- 320: # of Contacts (3: Row-to-Row Spacing)
- 300B: Contact Style
- CF: Closed Frame (Option)*
- R: Hi-Temp Material Call Out (Option)

Open frame is standard and available for all sizes and row-to-row spacing. Closed frame available in sizes shaded in table below. Add "CF" to the end of the p/n.

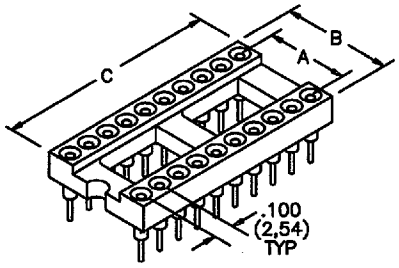
See page B1 for Material Call Outs

NO.OF CONTACTS	6	8	14	16	18	20	22	24	28	20	22	24	24	28	32	36	40	48	50	64
A	.300 (7,62)									.400 (10,16)			.600 (15,24)						.900 (22,86)	
B	.400 (10,16)									.500 (12,70)			.700 (17,78)						1.000 (25,40)	
C	.300 (7,62)	.400 (10,16)	.700 (17,78)	.800 (20,32)	.900 (22,86)	1.000 (25,40)	1.100 (27,94)	1.200 (30,48)	1.400 (35,56)	1.000 (25,40)	1.100 (27,94)	1.200 (30.48)	1.200 (30.48)	1.400 (35,56)	1.600 (40,64)	1.800 (45,72)	2.000 (50,80)	2.400 (60,96)	2.500 (63,50)	3.200 (81,28)

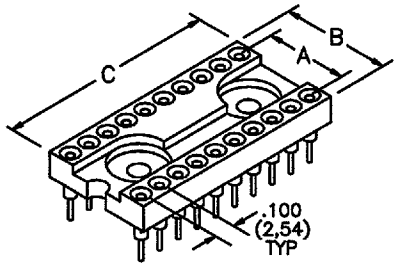
BERG ELECTRONICS

MK McKenzie Socket Division

Insulator Options



OPEN FRAME



CLOSED FRAME

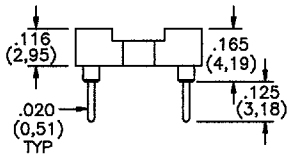
Insulators are
UL 94V-0 Rated
Thermoplastic

HIGH TEMP

AVAILABLE

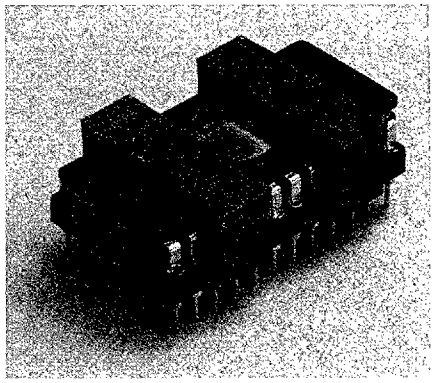
See page B1 for Hi-Temp Options

OUR MOST POPULAR CONTACT



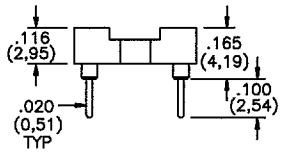
Specify	Contact/Shell
001B	30µ" Gold/200µ" Tin
002B	30µ" Gold/10µ" Gold
011B	10µ" Gold/200µ" Tin
014B	200µ" Tin/200µ" Tin
016B*	30µ" Gold/200µ" Tin
PTH =	.026 ± .003

**CLINCHABLE SOFT BRASS*

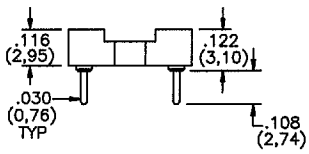


IC Retention DIP Clamps See Page B19

SHORTER SOLDER TAIL — NO TRIMMING

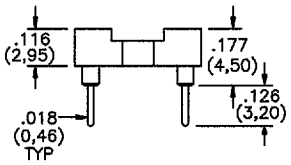


Specify	Contact/Shell
018B	200µ" Tin/200µ" Tin
PTH =	.026 ± .003

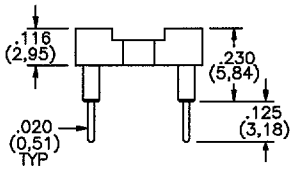


Specify	Contact/Shell
185B	30µ" Gold/200µ" Tin
PTH =	.036 ± .003

HIGHER PCB STANDOFF



Specify	Contact/Shell
248B	30µ" Gold/10µ" Gold
PTH =	.024 ± .003



Specify	Contact/Shell
040B	30µ" Gold/10µ" Gold
041B	30µ" Gold/200µ" Tin
PTH =	.026 ± .003

Contact/Shell:
Inner Contact — Beryllium Copper
Outer Shell — 1/2 Hard Brass

Plating:
Outer Shell — Gold over 100µ" Nickel or Tin over 100µ" Nickel
Inner Contact — Gold over 50µ" Nickel or Tin over 100µ" Nickel

Other contact and plating styles available, see Section A or consult the factory

INSULATORS	UL*	CONTINUOUS USE** TEMPERATURE	HEAT DEFLECTION** TEMPERATURE (@264 psi)
Hi-Temp - Vapor Phase and IR Compatible			
Polyimide Laminate (H), Glass Reinforced	94V-0	250°C	270°C
Fortron (PPS), (R), 40% Glass Reinforced	94V-0	220°C	260°C
Tefzel HT2004 (EPTFE),			
4% Glass Reinforced	94V-0		
8% Glass Reinforced	94V-0		
25% Glass Reinforced	94V-0	200°C	210°C
Vectra, C130 (LCP), (V)	94V-0	200°C	243°C
FR-4 Glass Epoxy (F)	94V-0	140°C	149°C
Standard Temp-Wave Solder Compatible			
Tefzel 280 (ETFE)	94V-0	150°C	74°C
Valox Polyester (420-SE0) (PBT)			
30% Fiberglass	94V-0	140°C	204°C
Zytel FR50, 25% Glass Reinforced Nylon	94V-0	130°C	240°C

**UL Flammability rating*

*** Typical value as defined by raw material supplier.*

OUTER SHELL AND TERMINAL MATERIALS – Screw Machine Sockets

Brass - Alloy 360, 1/2 hard, per QQ-B-626
Phosphor Bronze - Alloy 544 (B2), hard, per QQ-B-750, Comp. B

INNER CONTACT MATERIALS – Screw Machine Sockets

Beryllium Copper (BeCu) - Alloy 172, heat treated, per QQ-C-533
Beryllium Nickel (BeNi) - Alloy 440, heat treated

OUTER SHELL AND TERMINAL PLATINGS – Screw Machine Sockets

200µ" (nominal) BRIGHT ACID TIN per MIL-T-10727, Type 1 over 100µ" (nominal) Nickel per QQ-N-290
10µ" (nominal) GOLD per MIL-G-45204, Type 1 GRADE C, over 100µ" (nominal) Nickel per QQ-N-290
50µ" (nominal) GOLD per MIL-G-45204, Type 1 GRADE C, over 100µ" (nominal) Nickel per QQ-N-290
200µ" (nominal) TIN/LEAD (93%/7%) per MIL-P-81728, Type 1 over 100µ" (nominal) Nickel per QQ-N-290

INNER CONTACT PLATINGS – Screw Machine Sockets

10µ" (nominal) GOLD per MIL-G-45204, Type 1, GRADE C, over 50µ" (nominal) Nickel per QQ-N-290
30µ" (nominal) GOLD per MIL-G-45204, Type 1, GRADE C, over 50µ" (nominal) Nickel per QQ-N-290
50µ" (nominal) GOLD per MIL-G-45204, Type 1, GRADE C, over 50µ" (nominal) Nickel per QQ-N-290

All McKenzie Molded Insulators

®
Recognized

PERFORMANCE CHARACTERISTICS* — Screw Machine Sockets

Parameter	Value
Contact Resistance	<10 milliohms per contact
Contact Capacitance	0.3 pF
Contact Current Rating (for 10°C temperature rise)	3 A except for #6 (10) which is 2 A
Insulation Resistance (@ 500 V DC)	10,000 megaohms (min)
Contact Operating Temperature Range	-55°C to +150°C (BeCu) -55°C to +225°C (BeNi)
Dielectric Withstanding Voltage	1000 VAC
Rated Voltage	100 V AC
Durability	1000 cycles (min) @10 milliohms maximum change
Inner Contact Retention in Shell	7.5 lbs (3360 grams) minimum
Shell Retention force in Insulator (PGA's/DIP's)	10lbs (4480 grams) minimum

TEST CONDITIONS

Test	Results
Thermal Shock (IEC-68-2-14)	<2 milliohms change in contact resistance after 4 cycles (-10°C to +85°C)
Vibration (MIL-S-83505)	No electrical discontinuities or mechanical damage (10-2000Hz, 20G's, 1hr)
Solderability	Conforms to MIL-STD-202, Method 208
Shock (MIL-STD-202)	No discontinuities or mechanical damage (10 cycles of 200G's)
Temperature/Humidity Cycling (MIL-STD-1344)	<2 milliohms increase in contact resistance after 21 days, 40°C, 93% RH
Salt Spray (MIL-7344A)	<2 milliohms increase in contact resistance after 48 hrs, 35°C, 5% NaCi

**Unless otherwise stated*

SPECIFICATIONS

When applicable, McKenzie Technology's products and procedures are designed to meet the following general specifications:

MIL-STD 105	Sampling procedures
MIL-STD 109	Quality assurance terms and definitions
MIL-STD 202	Test methods for electronic and electrical components part
MIL-STD 1130	Connections, electrical, solderless, wrapped
MIL-STD 1344	Test methods for electrical connectors
MIL-STD 45662	Calibration system requirements
MIL-I-45208A	Inspection system requirements
MIL-C-39029	General specification for contacts, electrical connectors
MIL-S-83505	General specification for sockets (lead, electronic components)
ASTM-B487-79	Measuring metal\oxide coating thickness by microscopical examination of a cross section
ASTM-B567	Standard method of test for coating thickness by the Beta Backscatter principle
ASTM-A754-79	Standard method of test for coating thickness by X-ray florescence
MIL-M-24519	Molding plastics, electrical, thermoplastic
MIL-S-83734	Sockets, plug in electronic components, DIP, SIP, general specification for
MIL-P-13949	Plastic sheet, laminated, metal clad, general specification for